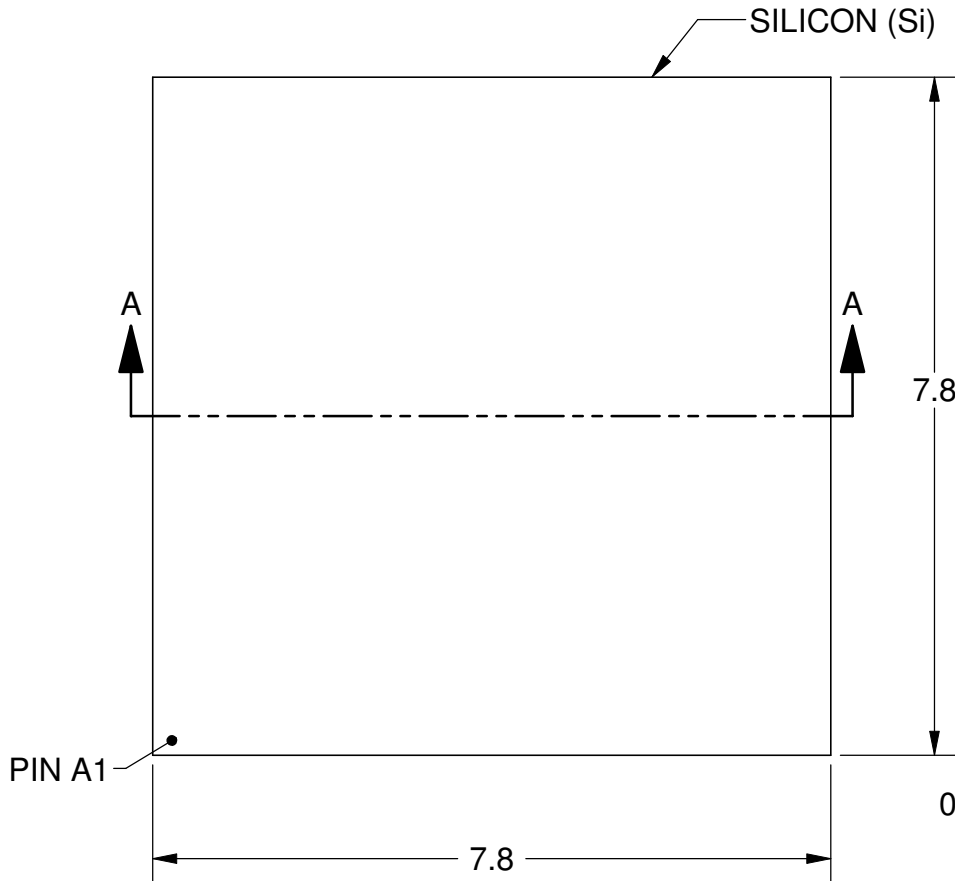
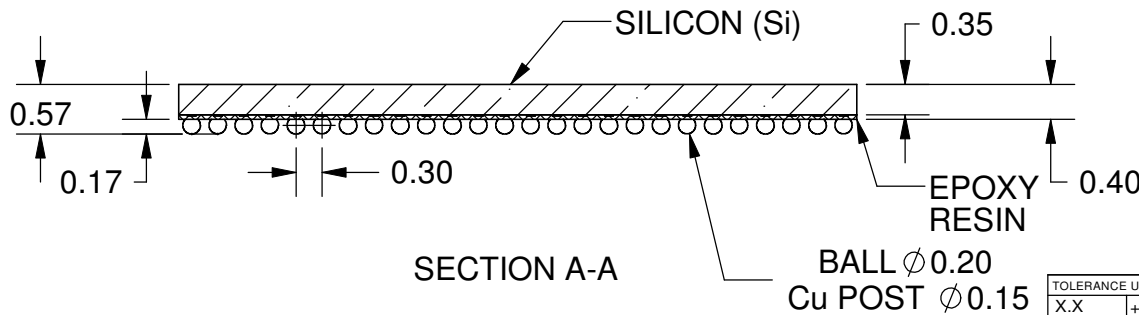
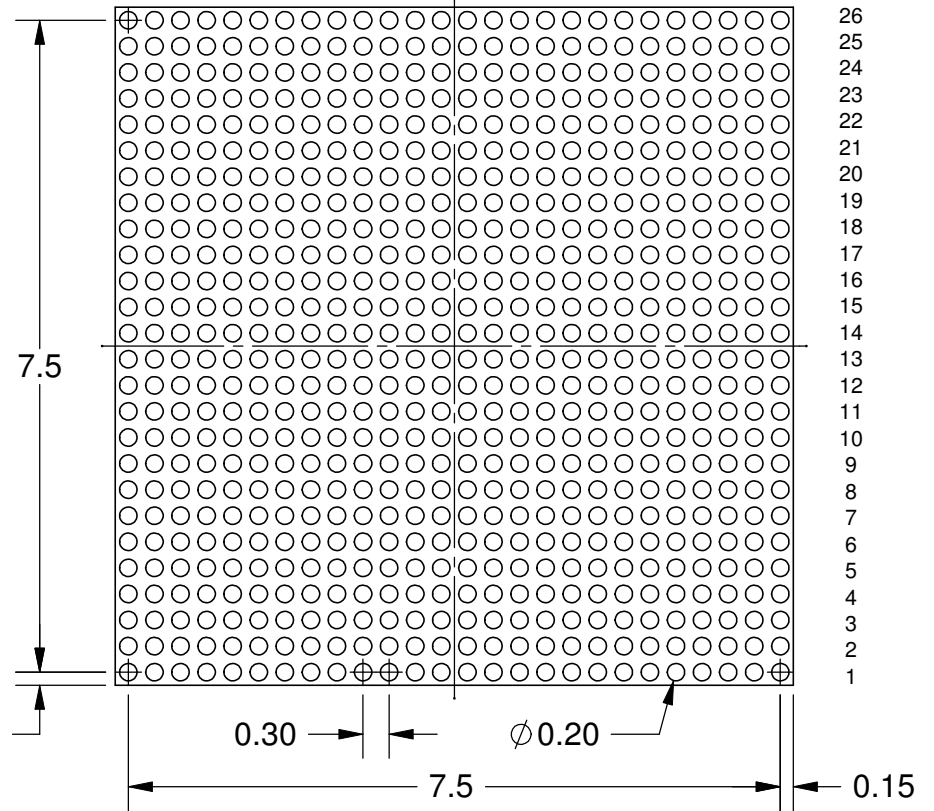


TOP VIEW



BALL VIEW

AF AD AB YW V U T R P N M L K J H G F E D C B A
AE AC AA



Notes: (Unless Otherwise Specified).

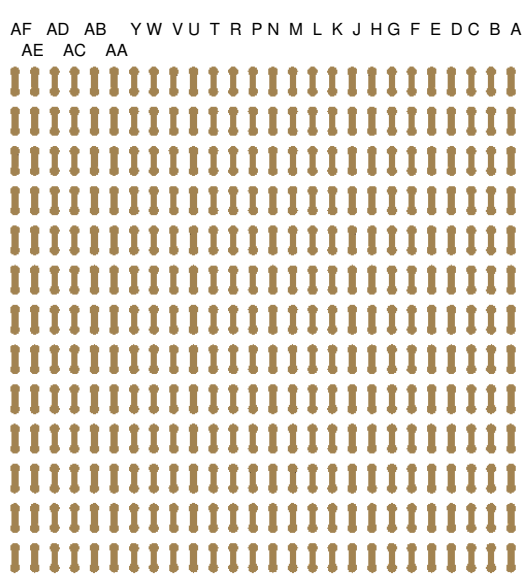
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY:
STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
SPECIAL: LF35 (Sn98.3/Ag1.2/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW): 0.20mm.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: 0.15mm.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP676T.3C-DC260D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
WLP676T.3C1-DC260D	Sn98.3/Ag1.2/Cu0.5	YES	YES	YES

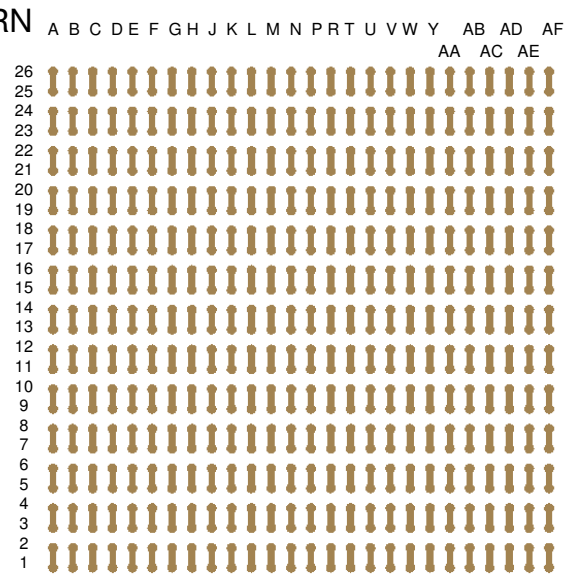
TOLERANCE UNLESS NOTED		APPROVALS	DATE
X.X	+/- 0.3	DRAWN J. Hines	12/29/2010
X.XX	+/- 0.03		
X.XXX	+/- 0.003		
ANGLES +/- 0.5°		ENG	
ALL DIMENSIONS IN		MFG	
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		QA	
THIRD ANGLE PROJECTION		CUST	
		REVISED	

TopLine ®			
TITLE WLP676T.3C-DC260D			
676-BALL P=0.3mm (TEG0306)			
SCALE 11.5:1	SIZE A	DRAWING NO. 532602	REV A
DO NOT SCALE DRAWING			SHEET 1 OF 2

BALL VIEW

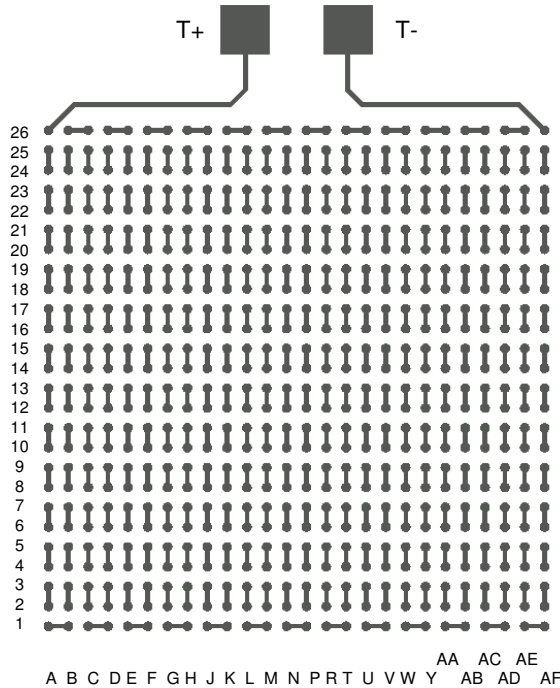


DAISY CHAIN PATTERN

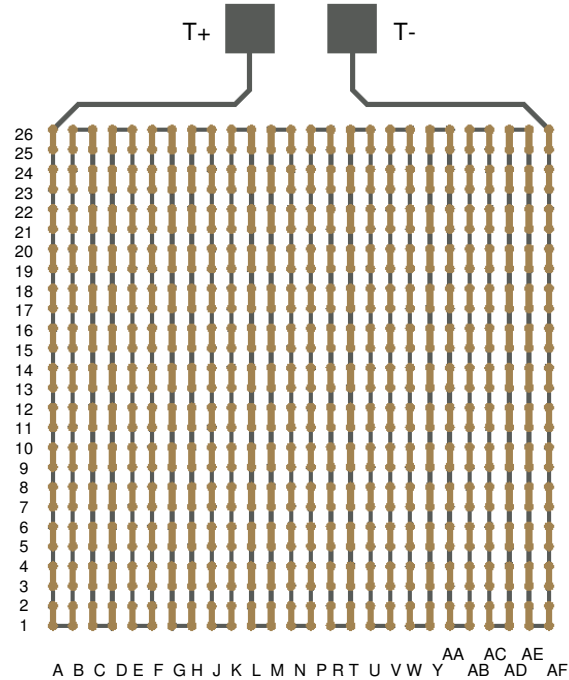


BOTTOM SIDE
(TOP X-RAY VIEW)

TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.15mm (5.9mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.07mm (3mil).

TopLine ®			
TITLE WLP676T.3C-DC260D 676-BALL P=0.3mm (TEG0306)			
SCALE 8.75:1	SIZE A	DRAWING NO. 532602	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	